

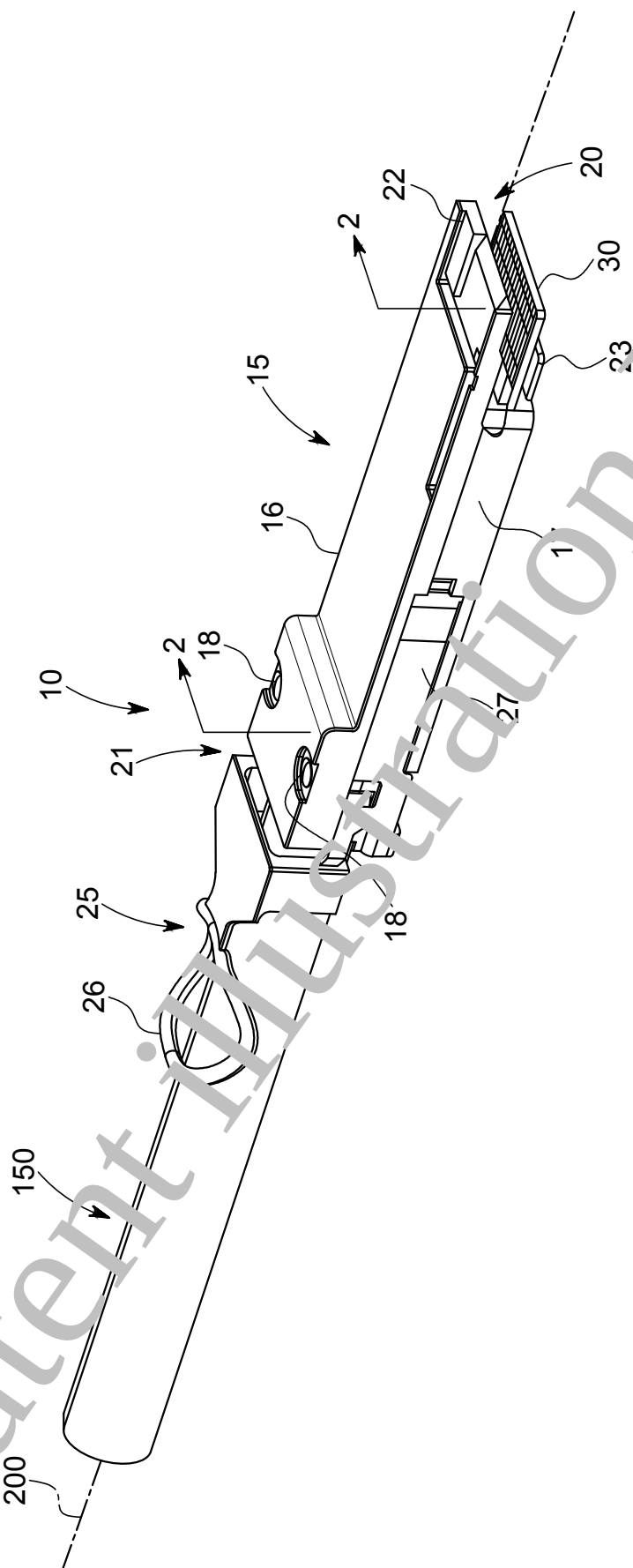


Fig. 1

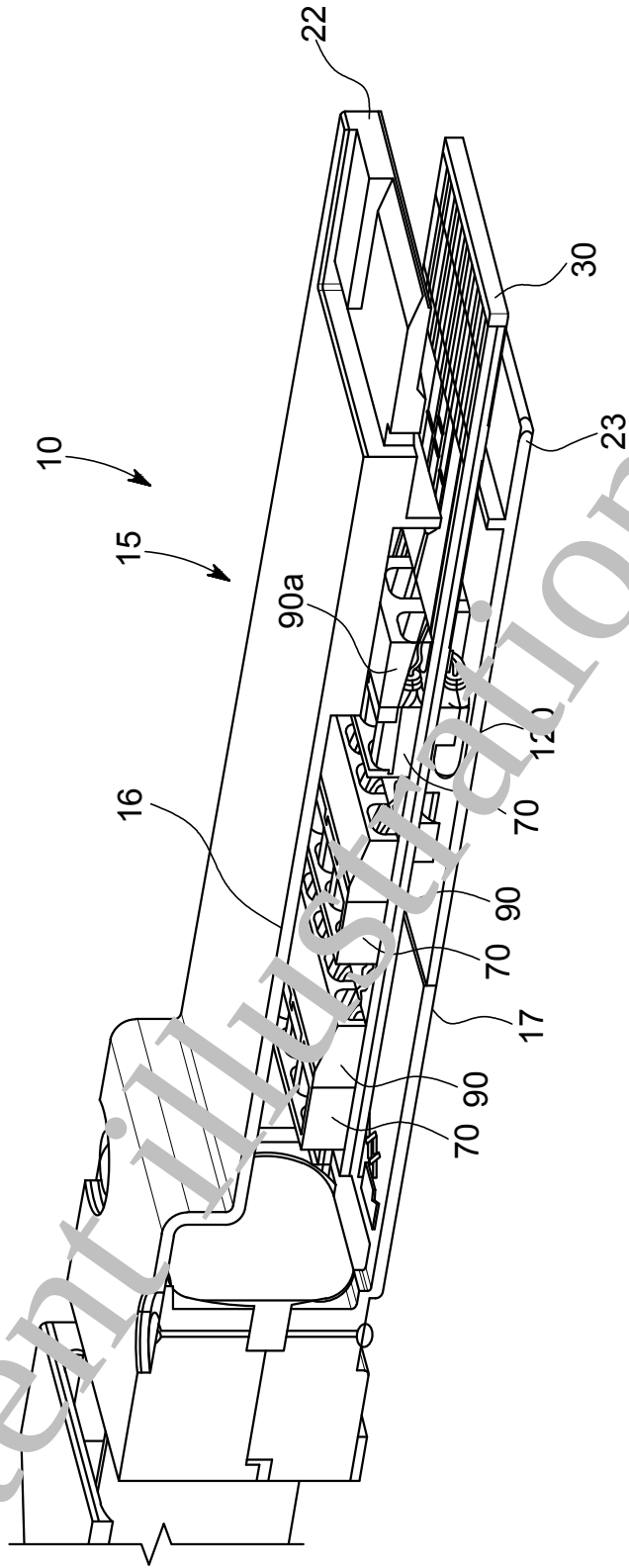


FIG. 2

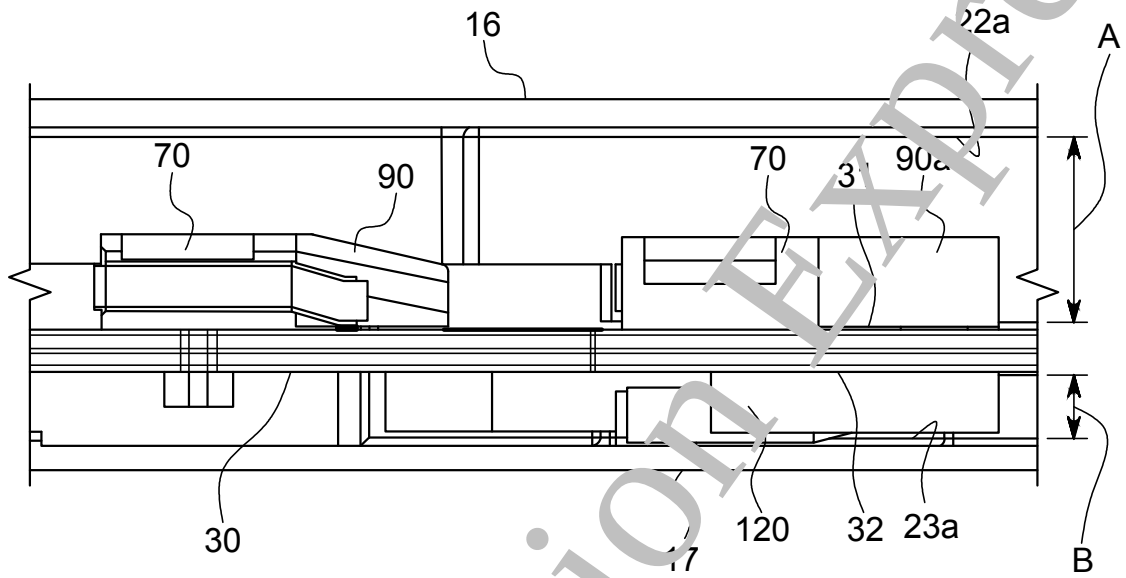


FIG. 3

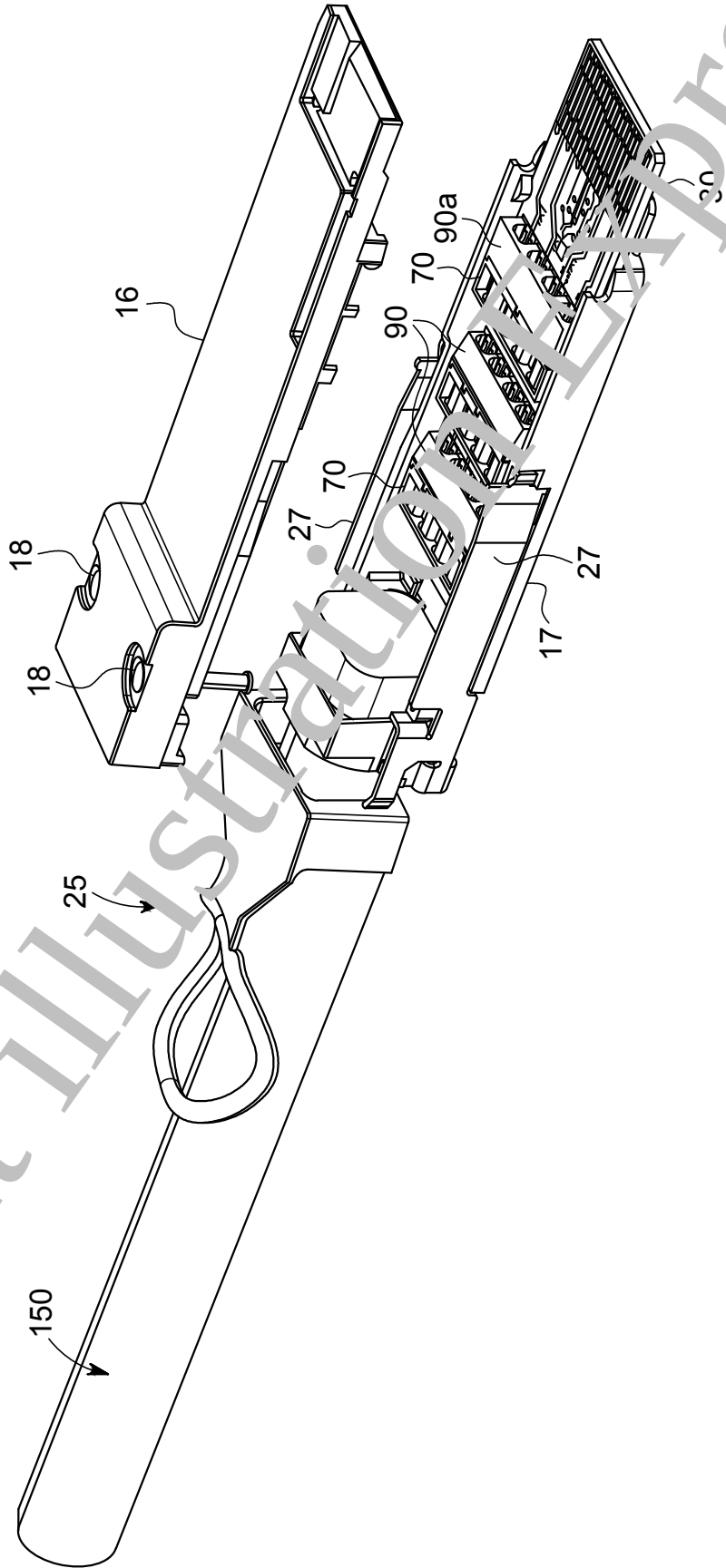


FIG. 4

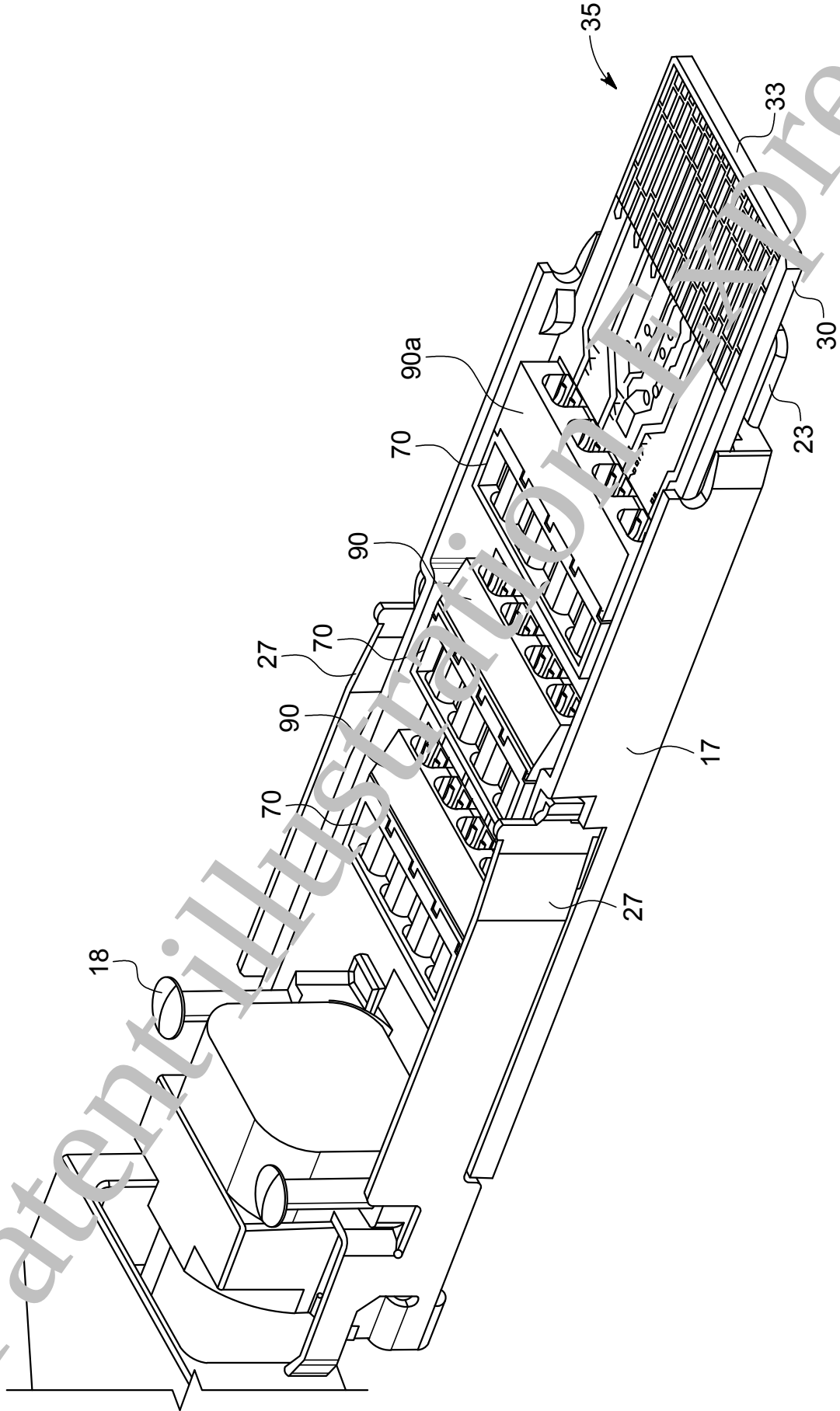


FIG. 5

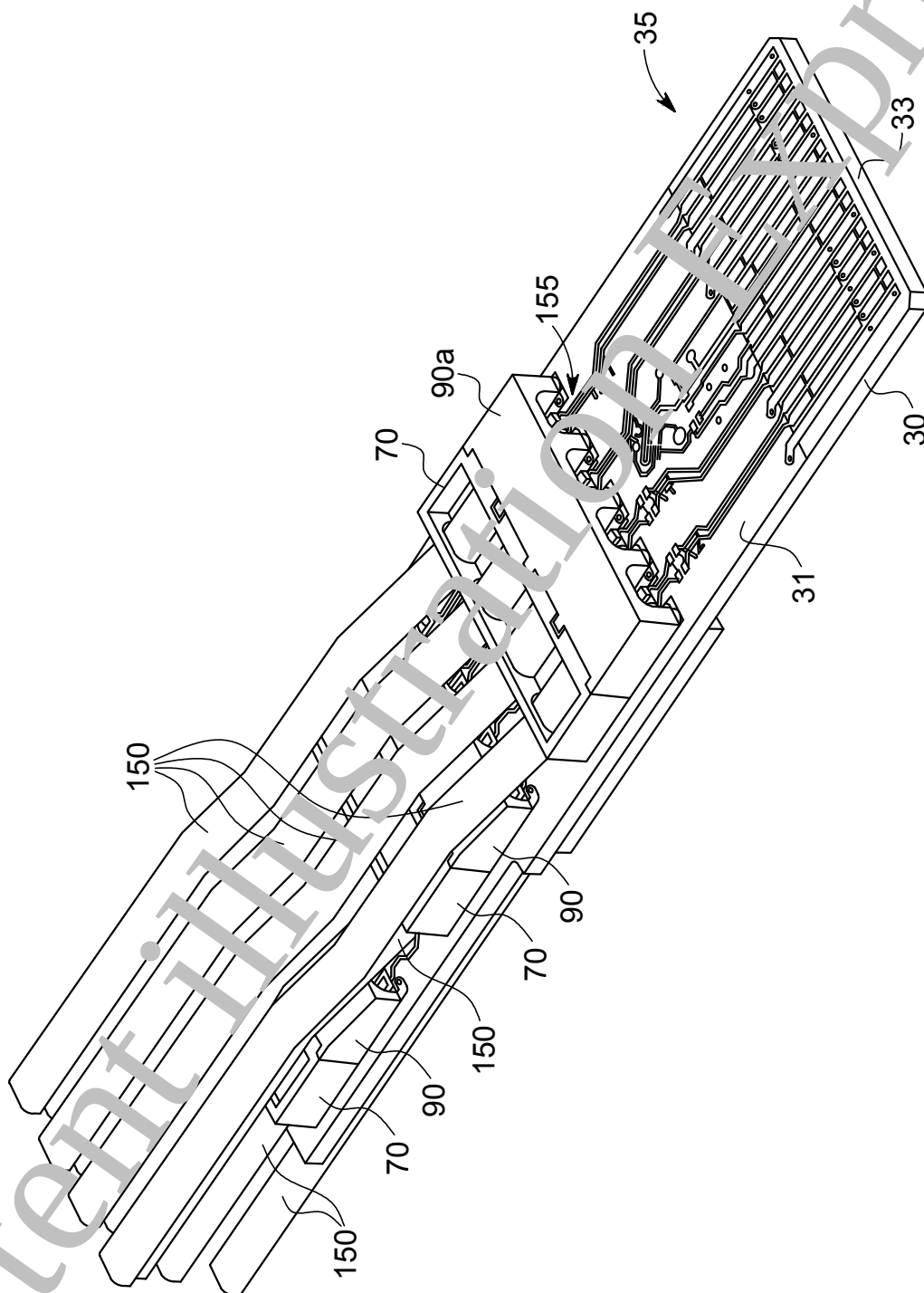


FIG. 6

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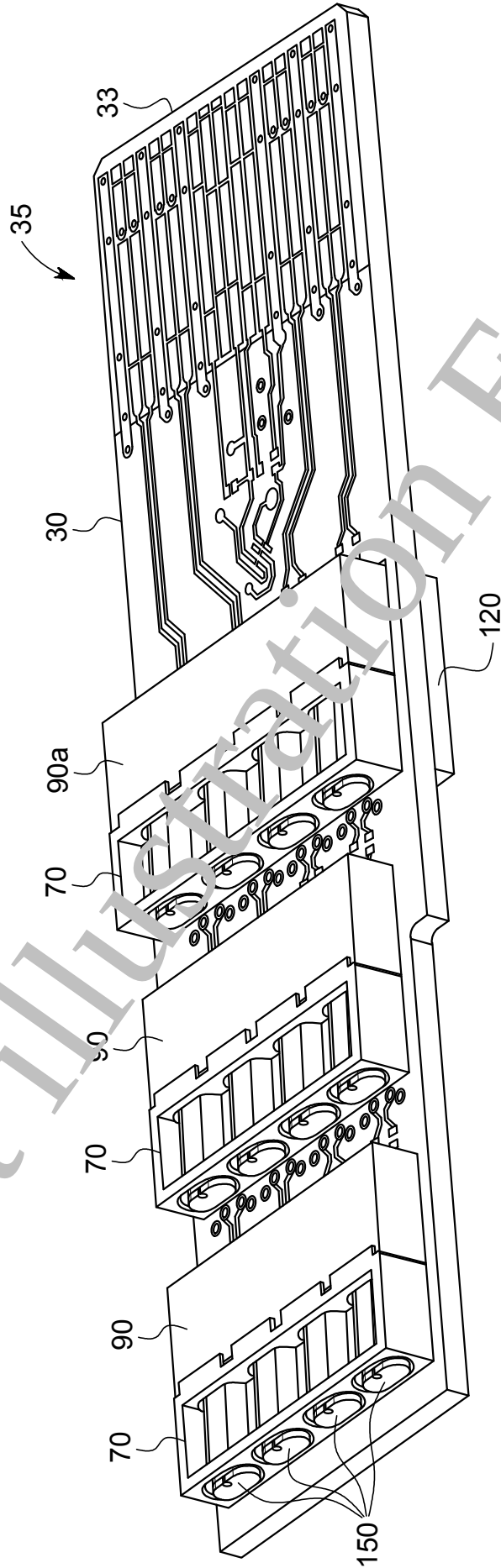


FIG. 7

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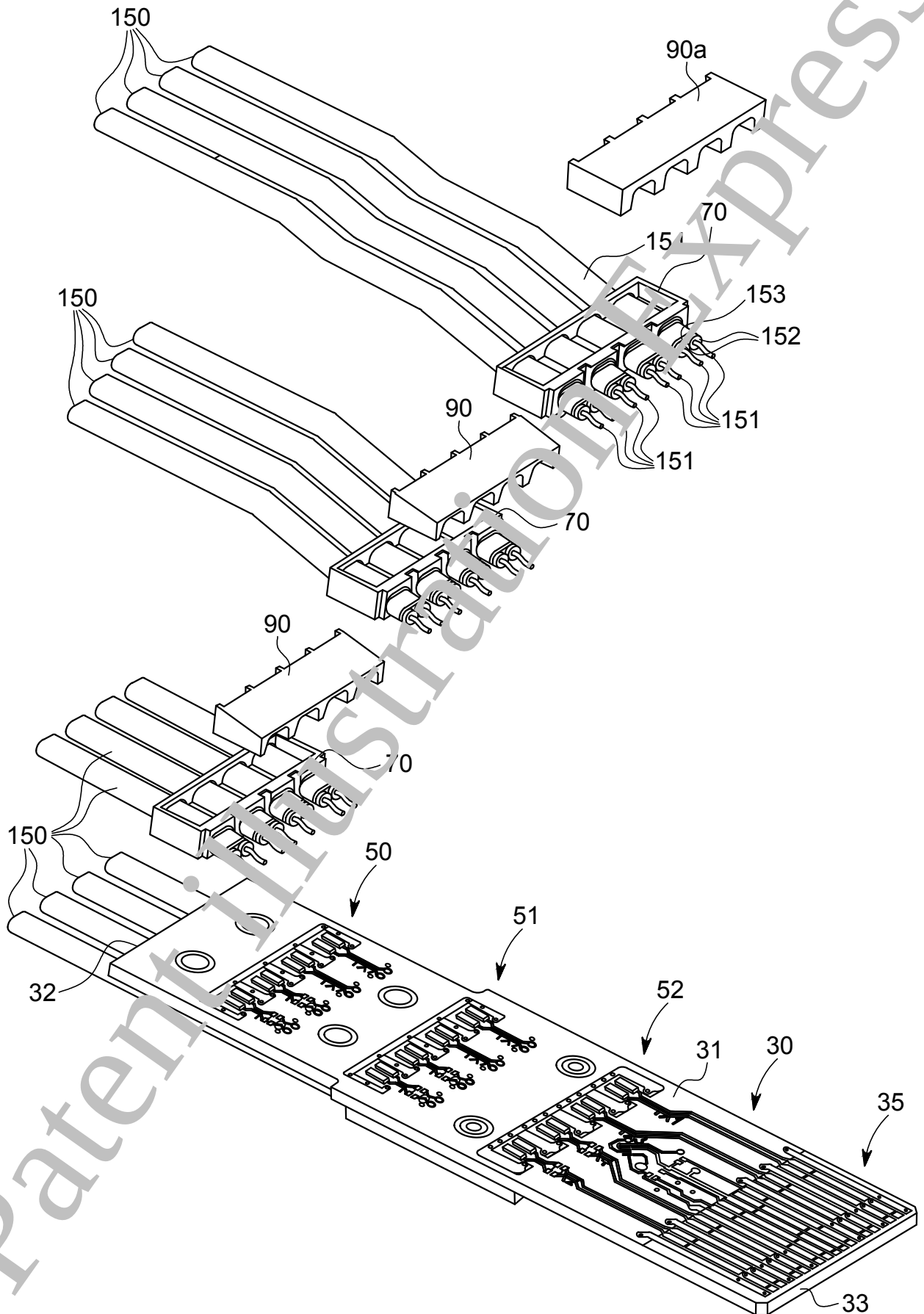


FIG. 8



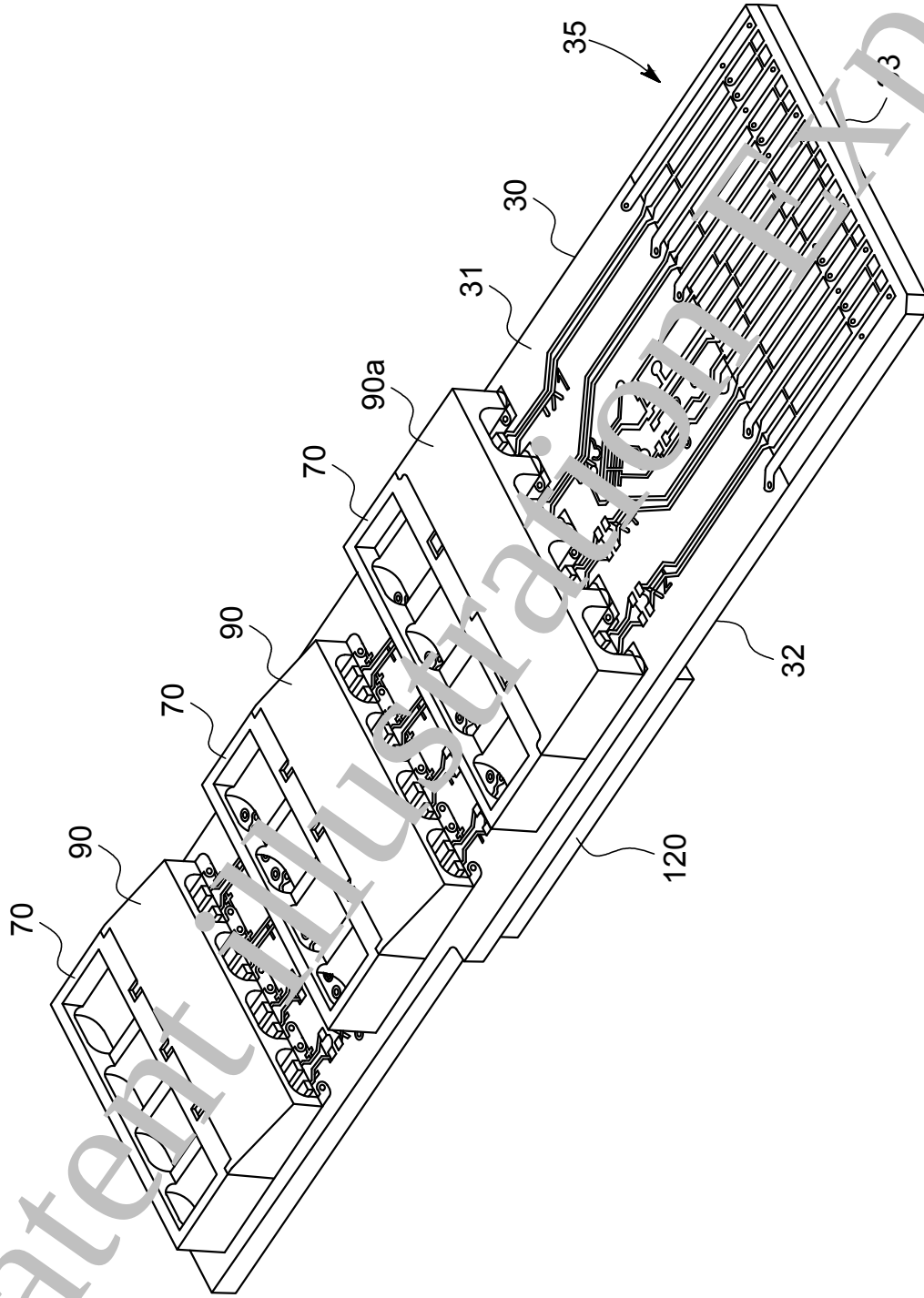


FIG. 9

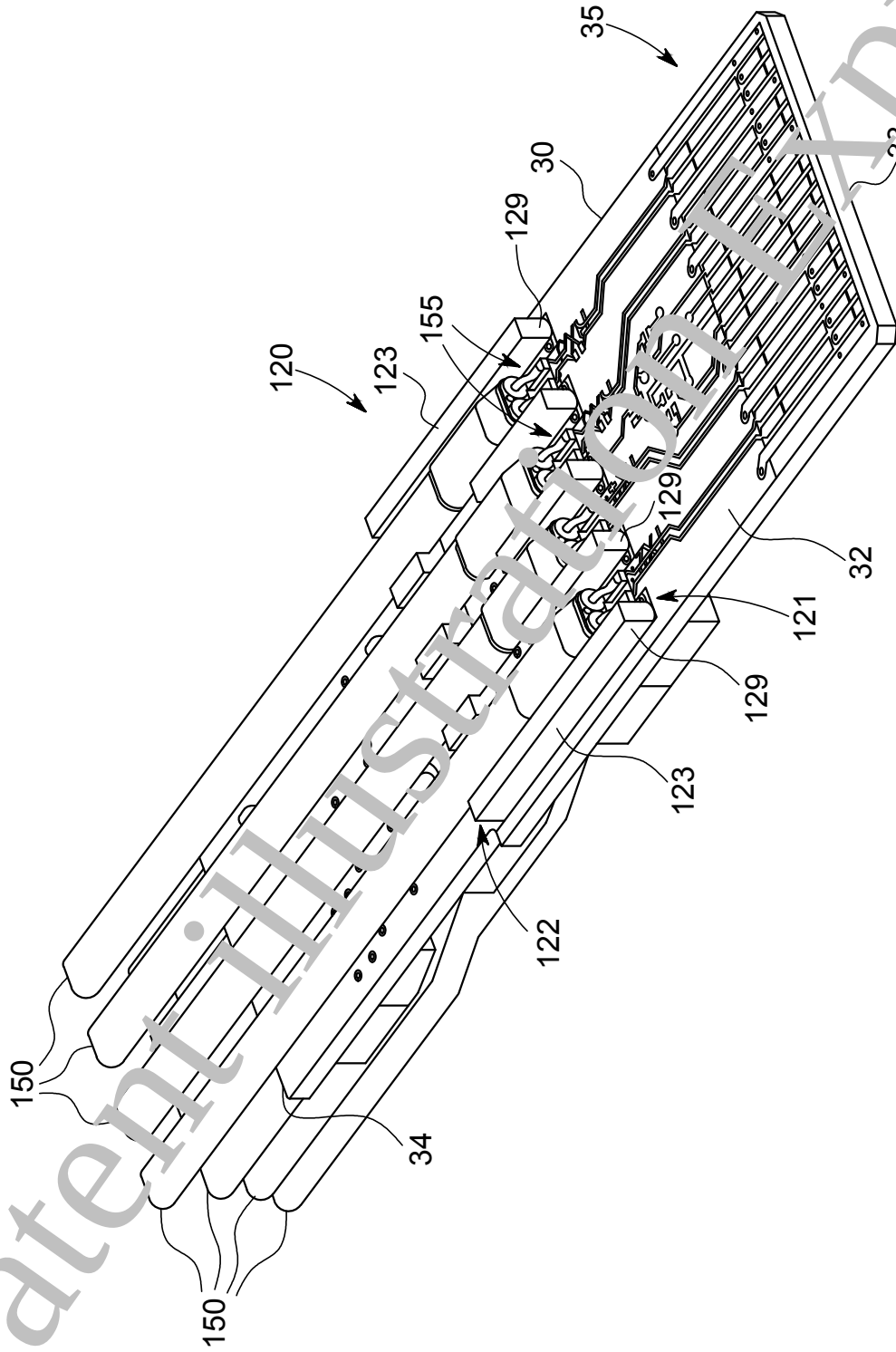


FIG. 10

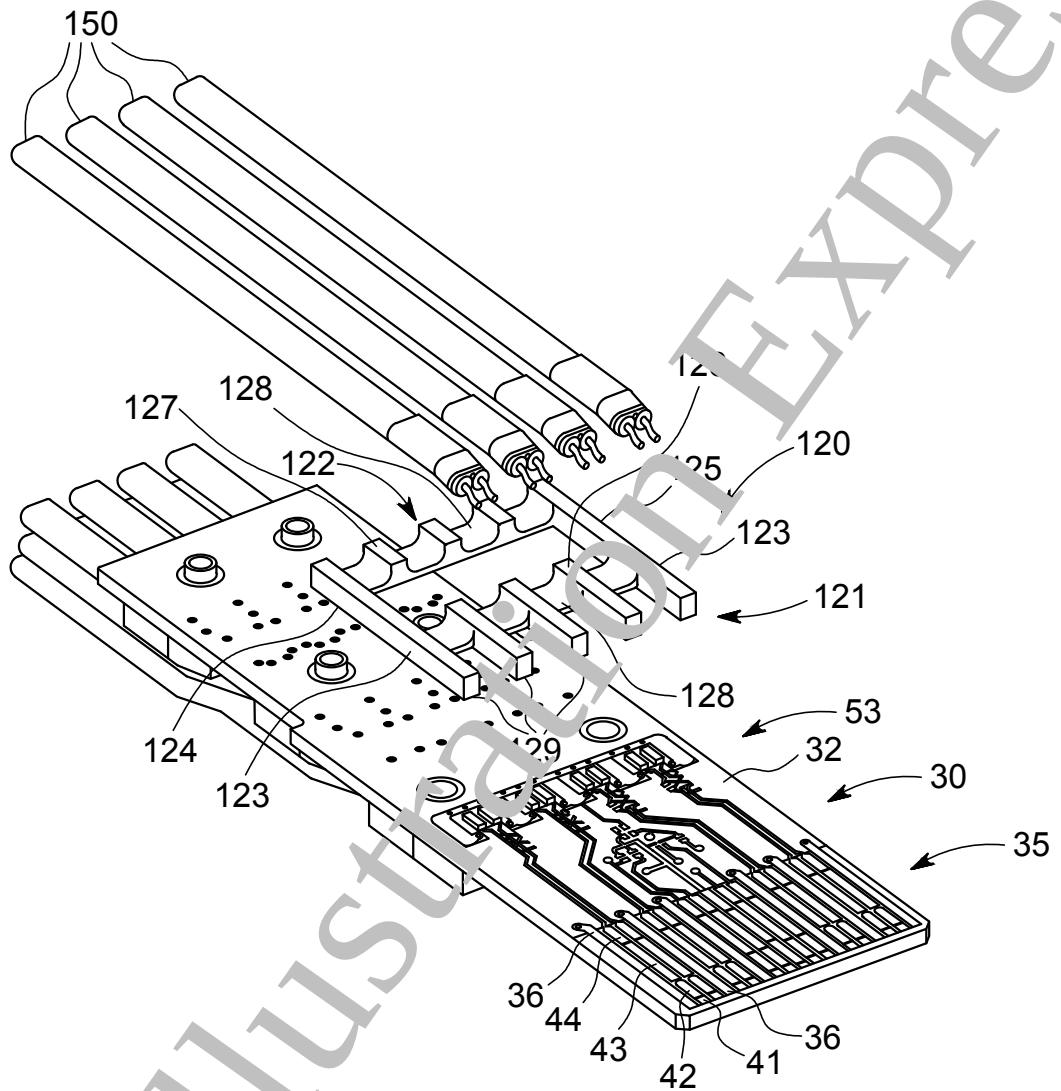


FIG. 11

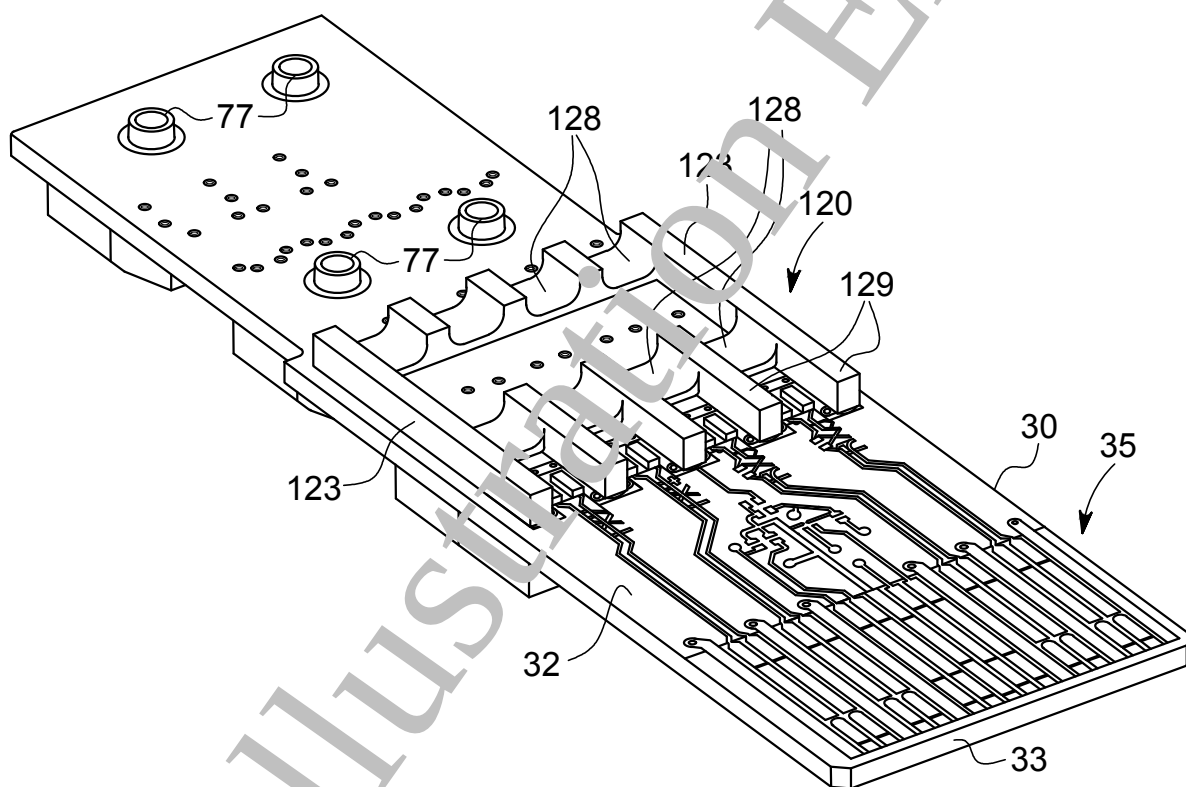


FIG. 12

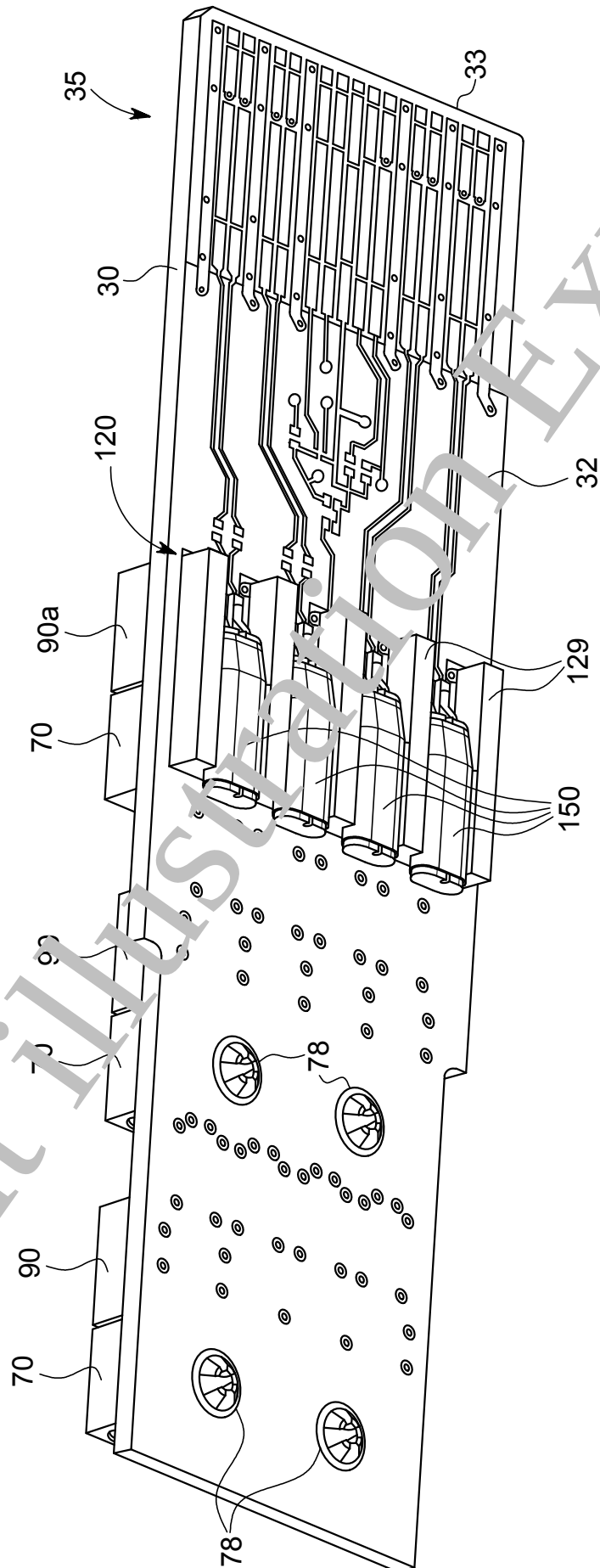


FIG. 13

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FIG. 14

FIG. 14 is a detailed cross-sectional view of a multi-layer printed circuit board (PCB) assembly. The assembly consists of a top layer (30) and a bottom layer (34) separated by a core (32). The top layer features a complex network of conductive traces (35, 36, 40, 41, 42, 43, 44) and vias (66). A central component (51) is mounted on the top layer, with various electrical connections (52, 55, 56, 67) leading to it. The bottom layer also has conductive traces (37, 38, 39) and vias (66). The entire assembly is shown within a dashed rectangular boundary (200).

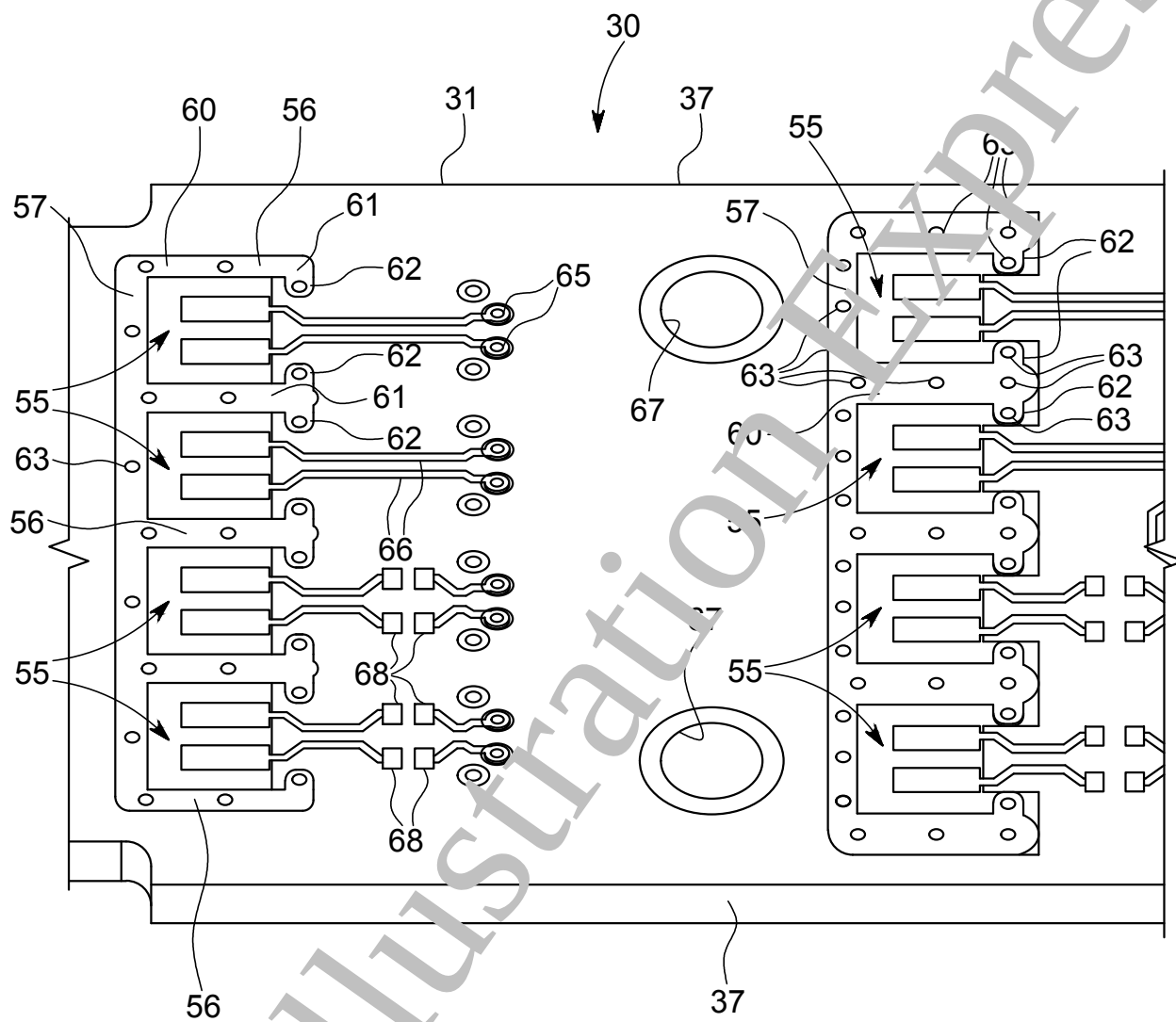


FIG. 15

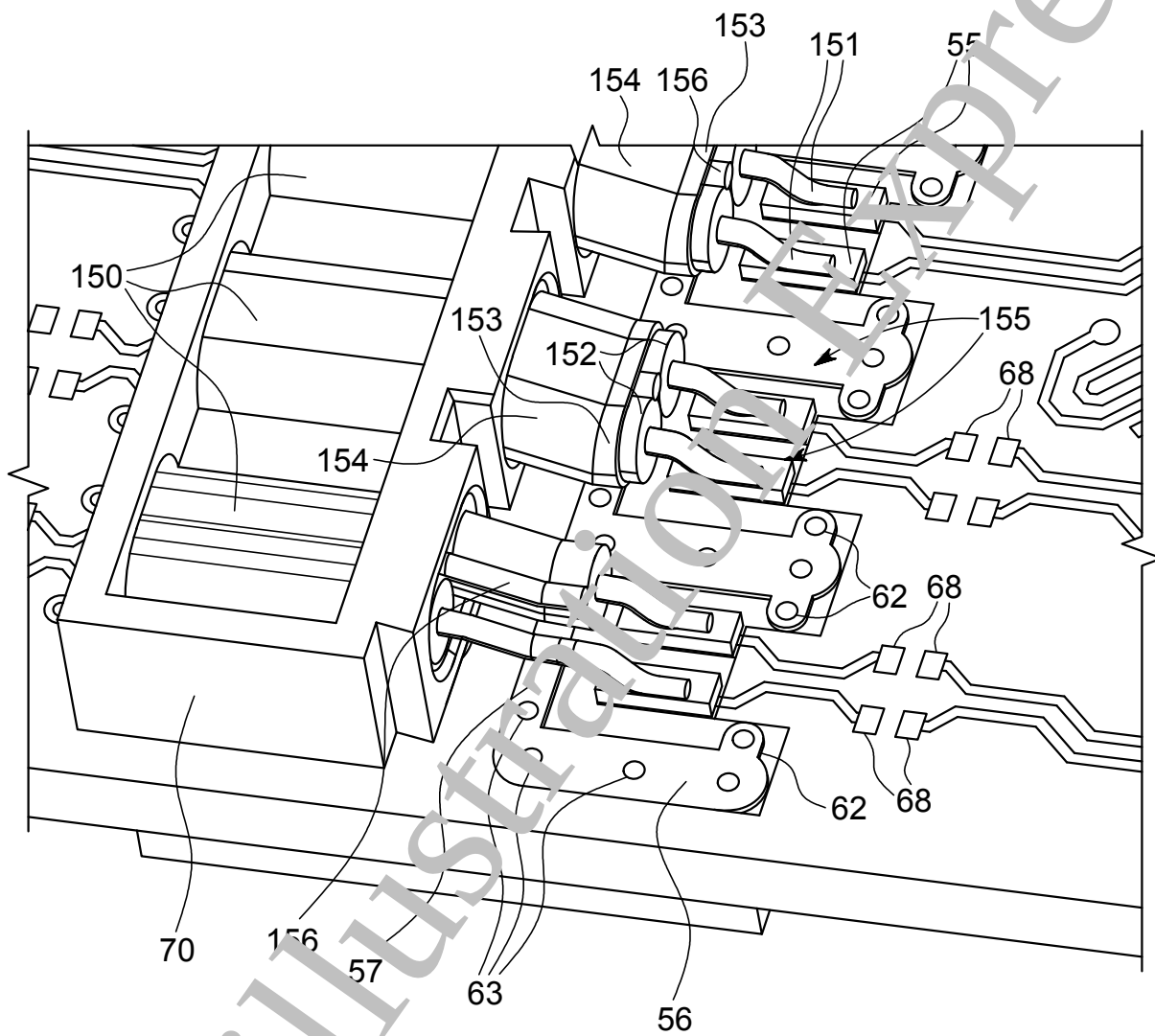


FIG. 16



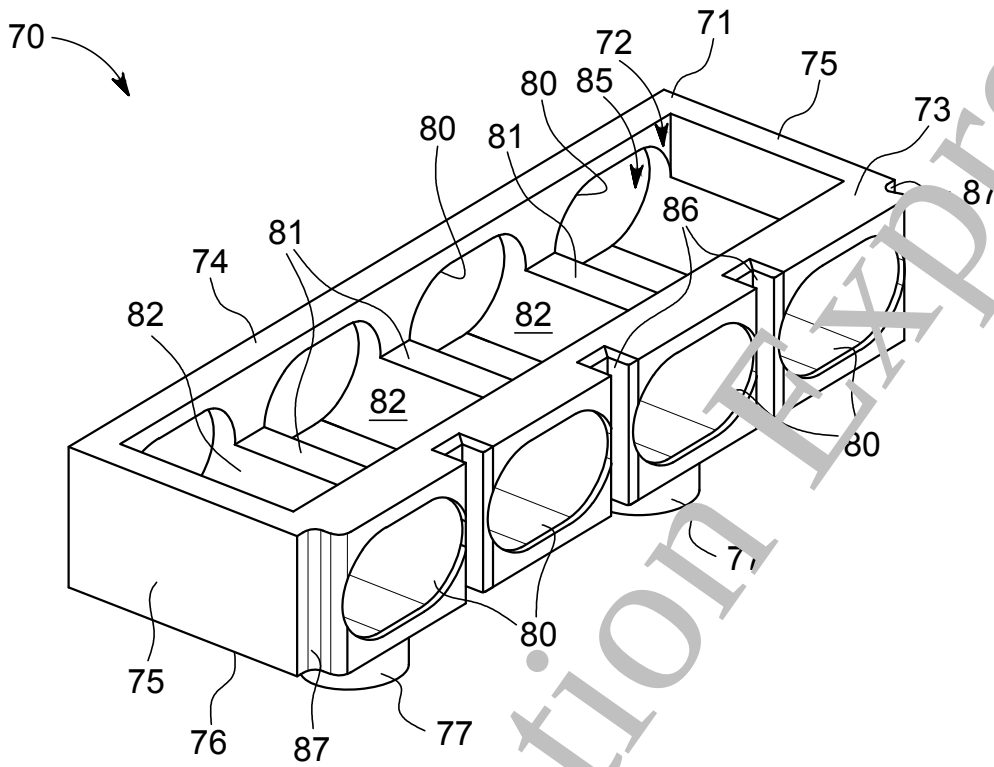


FIG. 17

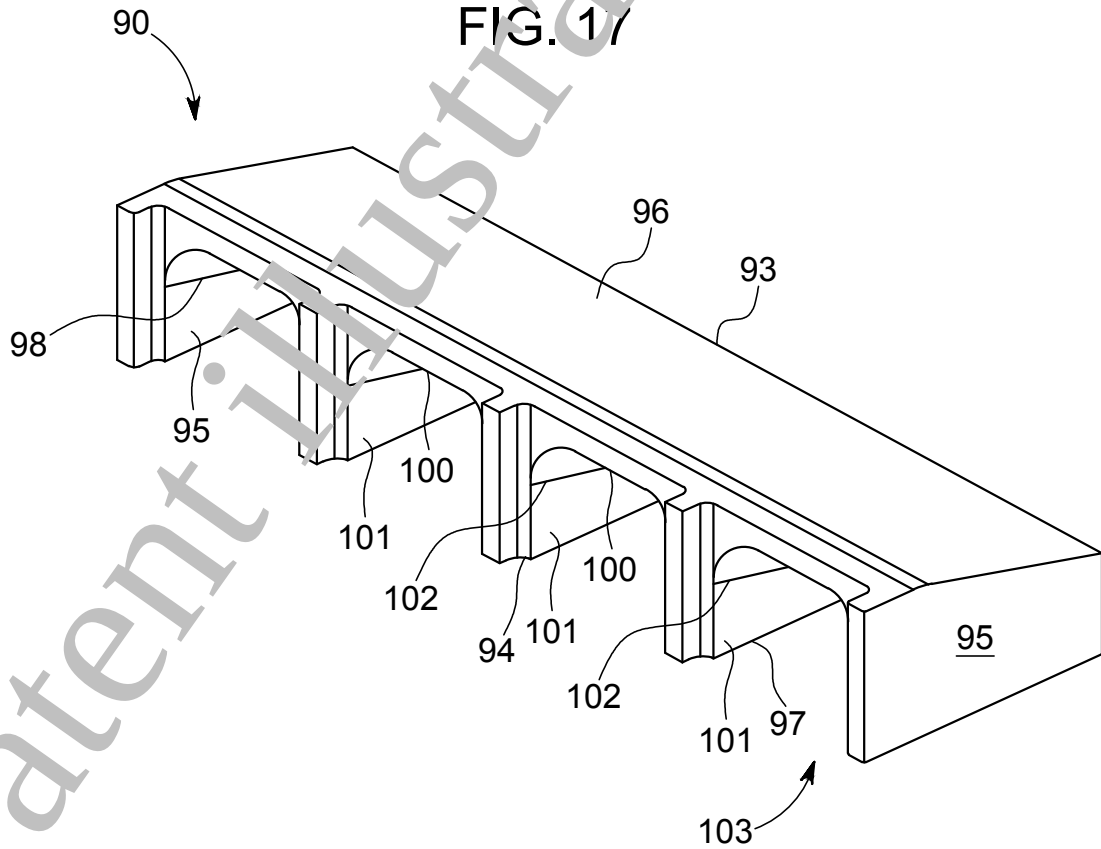


FIG. 18

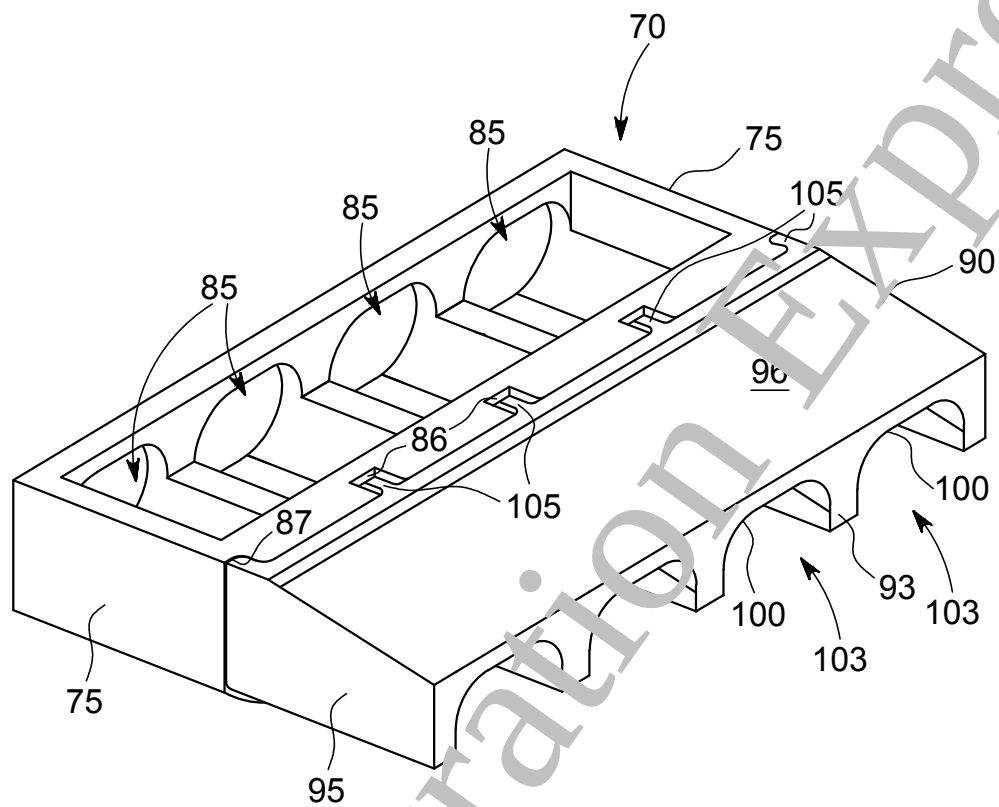


FIG. 19

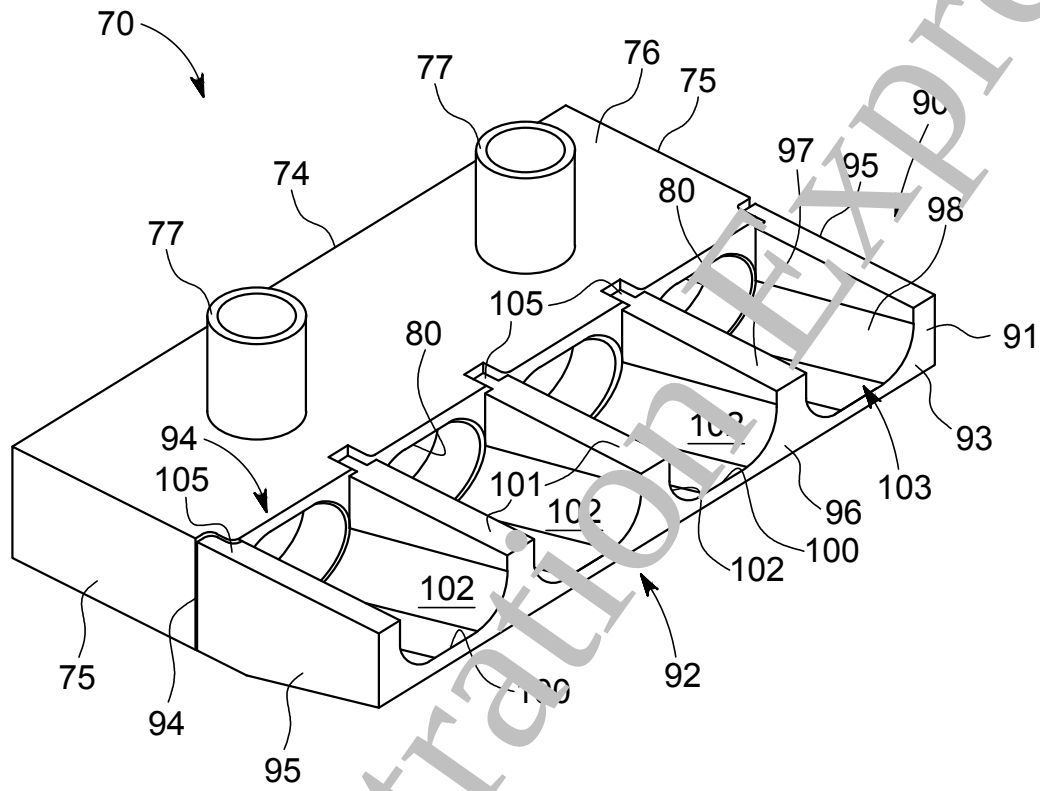


FIG. 20

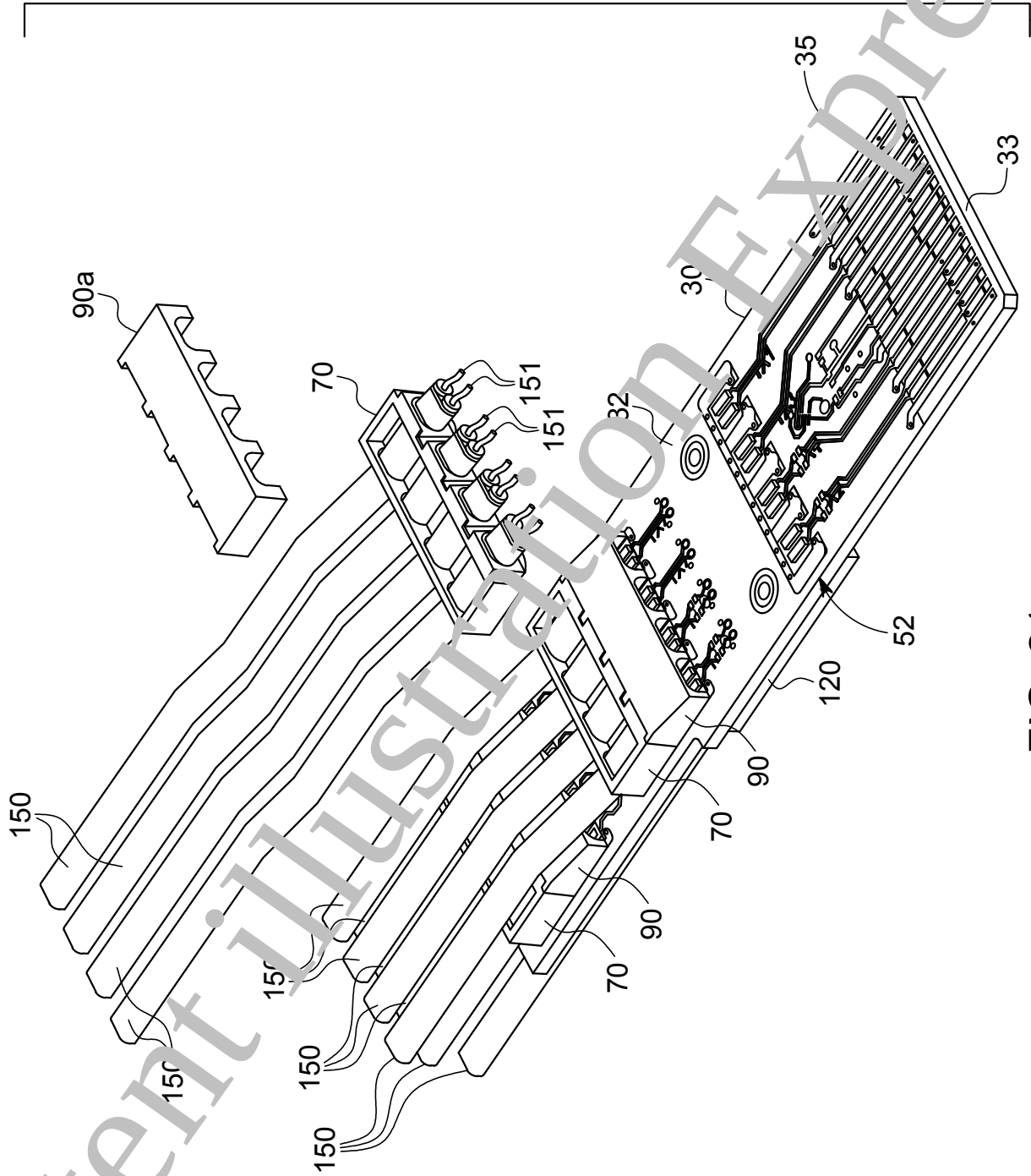


FIG. 21

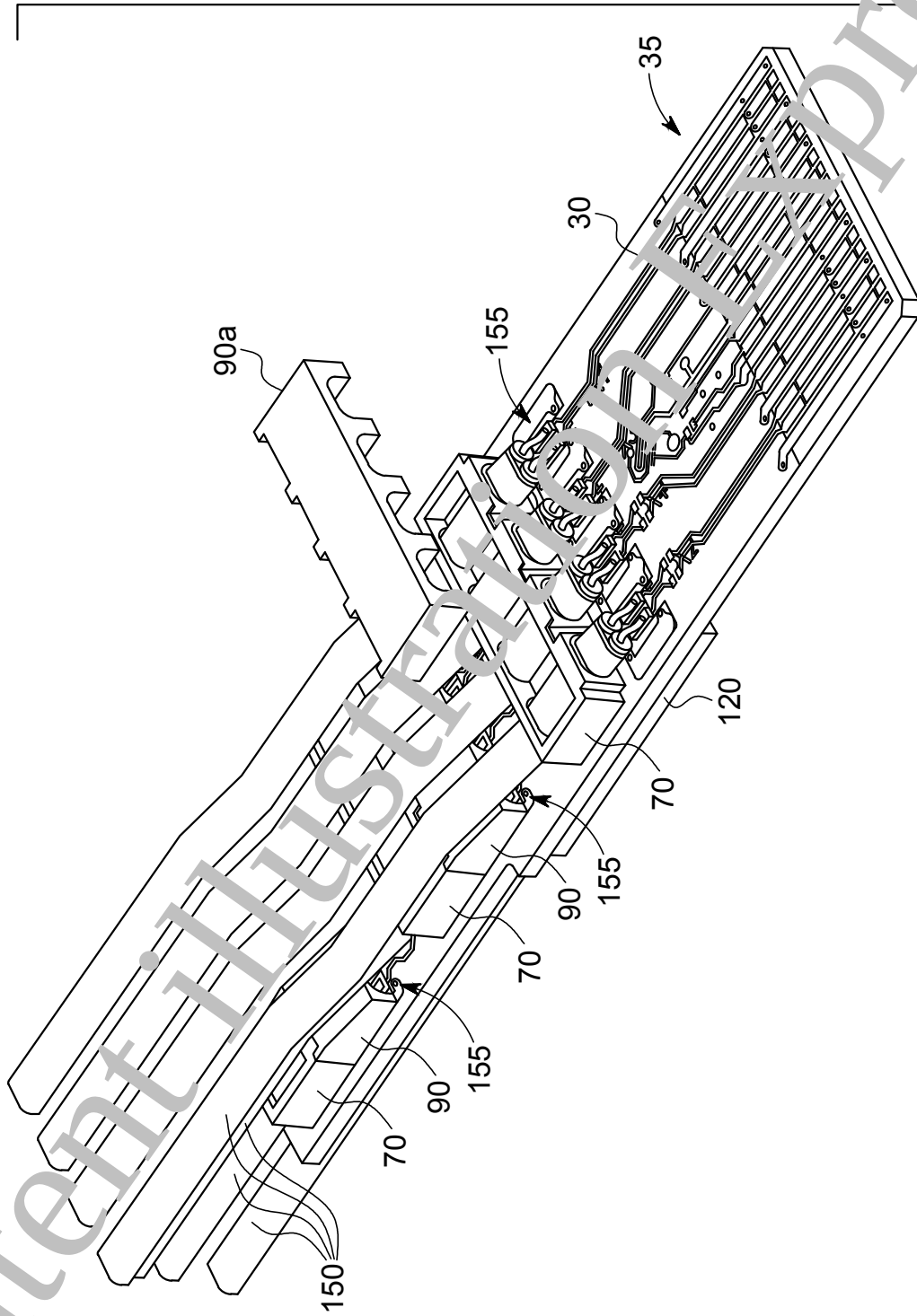


FIG. 22

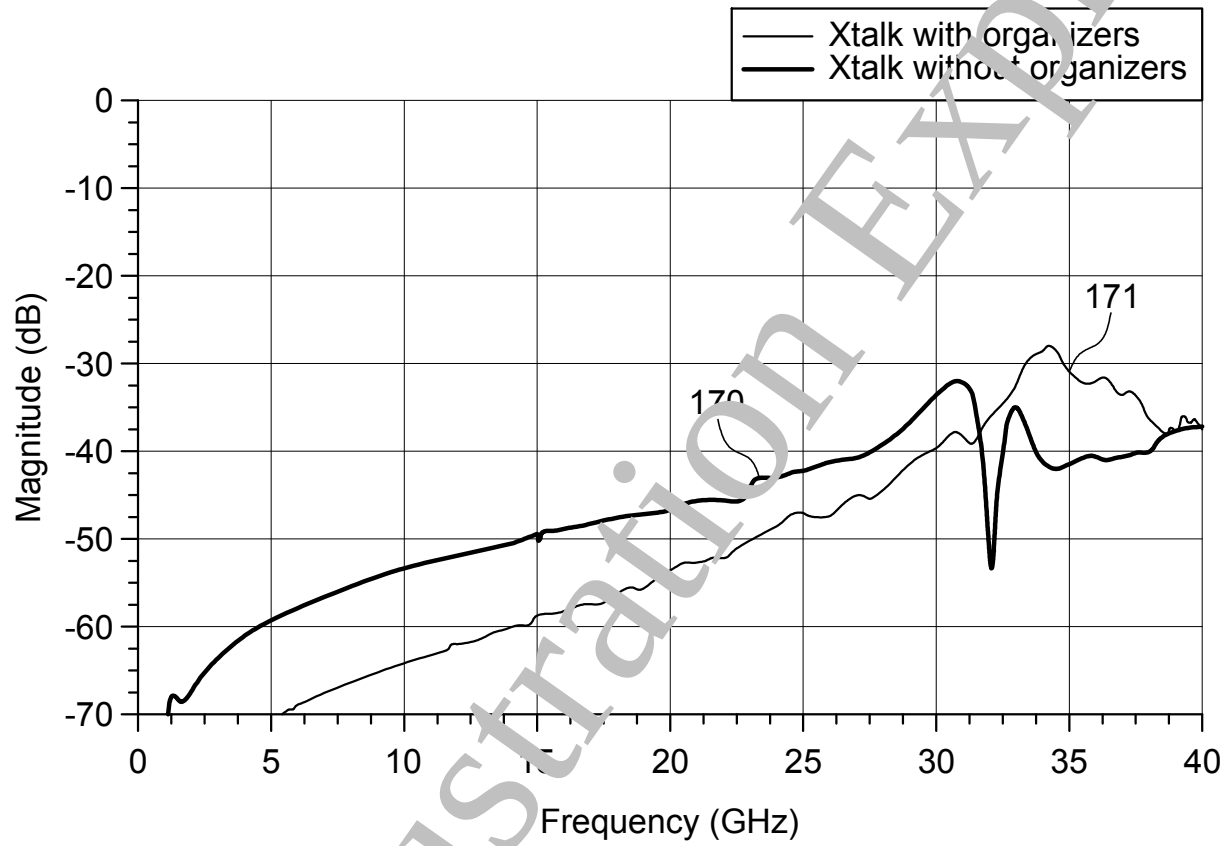


FIG. 23

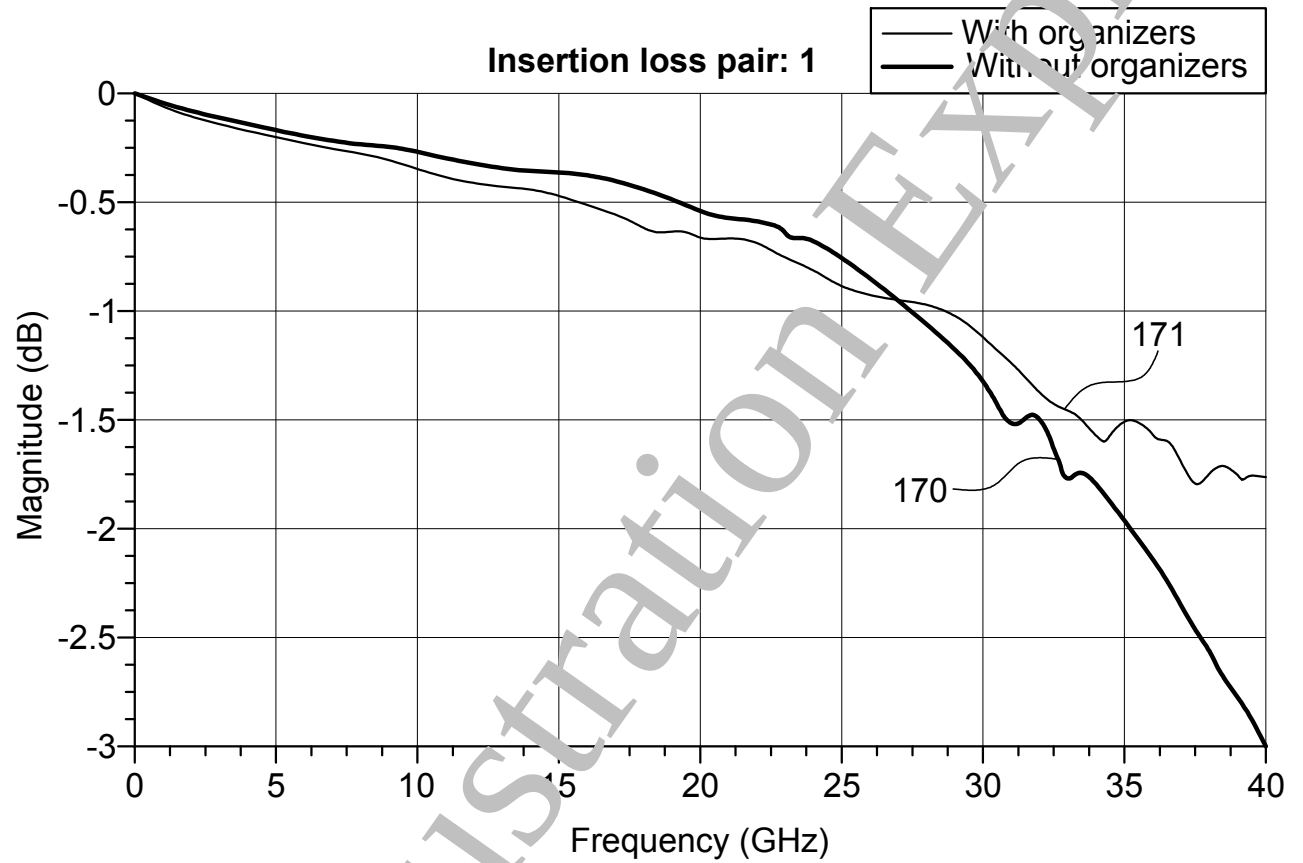


FIG. 24

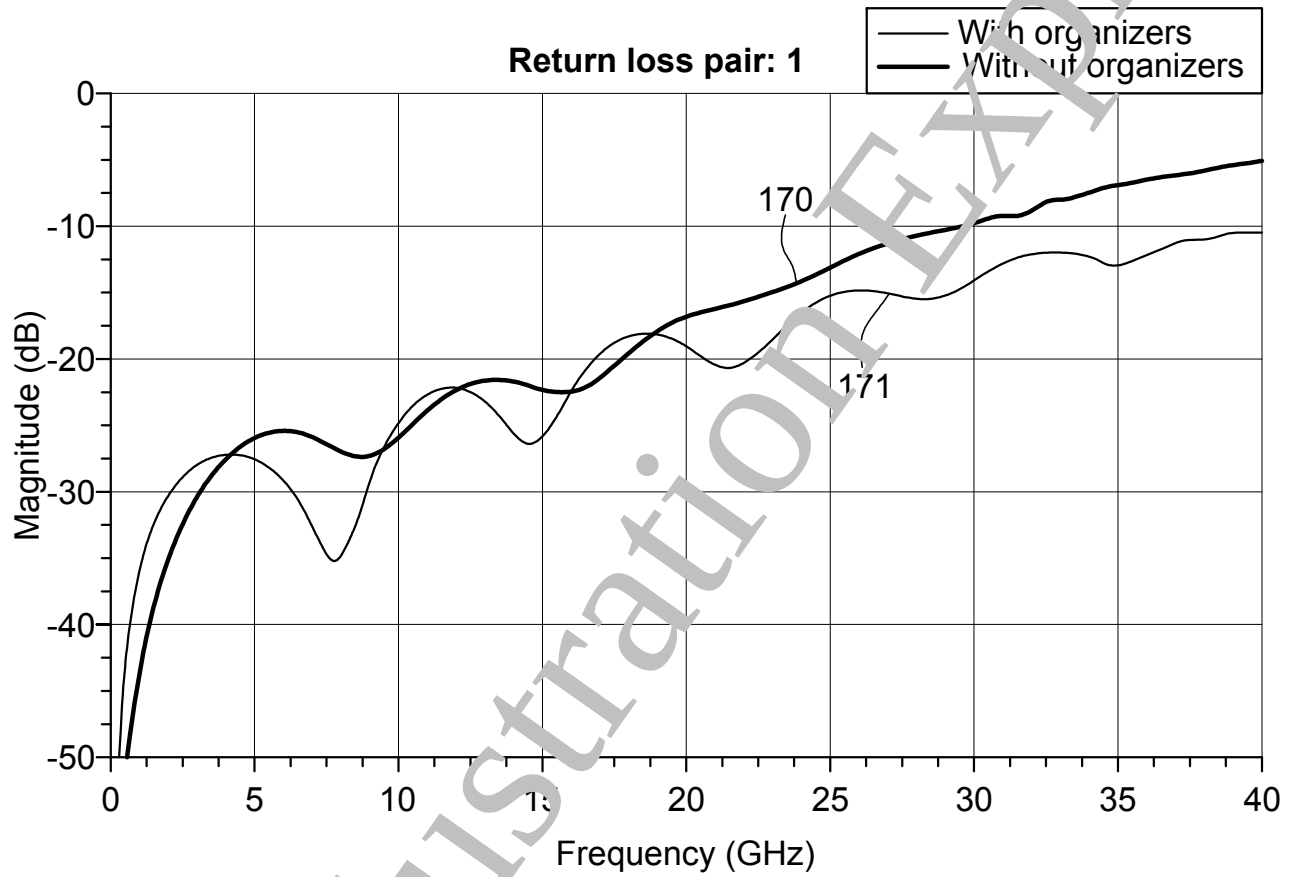


FIG. 25



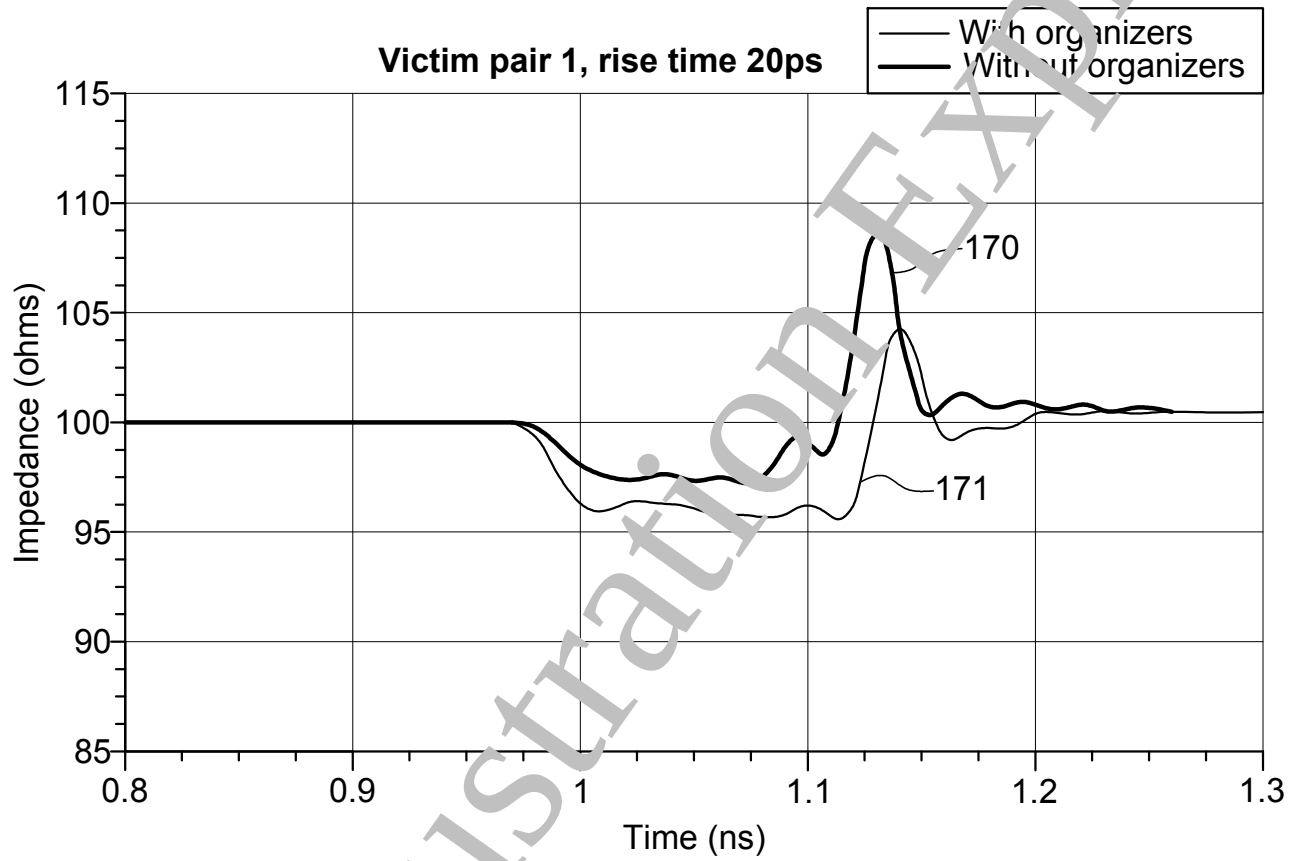


FIG. 26